



FLUIDEL 5 SOLDER WIRE

ALLOY Sn**Pb** - "HC3"

The alloy and flux combinations are designed to be used for the soldering of printed circuits boards and metal part components to the highest standards. They are produced from very high quality materials to international standards.

Chemical Characteristics

Amount of Tin:	** % \pm 0.5%
Amount of Lead:	** +/- 0.2%

Tin and lead of first smelting.
Chart of typical maximum impurities:

Cu	Ag	Cd	Sb	Fe
0.05%	0.005%	0.002%	0.05%	0.02%

Zn	Al	S	Cl	P
0.001%	0.001%	0.001%	0.001%	0.001%

Others
0.05%

Type of incorporated flux: Hydrosoluble Inorganic:
HC3 – Acid Core

Available also in lead free alloys.

Physical Characteristics, standard:

*ALLOY	
Melting point	Alloy dependant
Specific weight	\sim 8.5 g/cm ³
Wire dimensions	Diameters from 0.5mm to 5mm
Working temperature	350 to 450 °C

*FLUX

- Hydrosoluble inorganic
- Amine 6.5 %
- Acidity index : 220
- Amount: Grade 1, Grade 2 or Grade 3 (BS441)

Packaging

- Supplied on spools: 250g, 500g, 1kg and 3kg.
- Packed in cartons of: 20 x 250 g, 20 x 500g, 16 x 1kg and 6 x 3kg. (Others : consult customer services)
- Boxes and bobbins carry information labels and manufacture lot numbers.
- Quality assurance: Certificates of Conformity can be issued for each shipment batch if requested at the time of ordering.
- Health and safety information available on request.